Category Award IC & Components

6.7 mm Smaller Footprint e.MMC

ATP Electronics, Inc.
華騰國際科技股份有限公司

Winning Reason

Introducing the world’ s first 6.7mm ultra-thin e.MMC, a breakthrough storage solution meticulously engineered for the multi-billion dollar wearables market. Departing from the bulk and high energy demands of traditional e.MMC, this compact chip seamlessly integrates into ultra-slim frames, making it the ideal storage solution for space-constrained devices like smart glasses and AR eyewear. Featuring Auto Power-Saving technology, it reduces power consumption by up to 70% under real-world workloads, significantly extending battery life. Built with 3D TLC NAND and high-reliability firmware, it minimizes failure rates and electronic waste, setting a new standard for sustainable tech.

Product Feature

This product is the industry’ s first and world’ s smallest 6.7 mm e.MMC, with an ultra compact 6.7 x 7.2 x 0.65 mm 125 ball FBGA package about 67% smaller than standard e.MMC, ideal for next generation smart wearables where every millimeter and milliwatt count. The ultra thin 0.65 mm z height is tailored for slim smart glasses frames, blending seamlessly with technical, ergonomic, and aesthetic requirements. It pairs with discrete LPDDR and major SoC platforms to create a highly integrated, space efficient memory subsystem. Power optimized firmware with Auto Power Saving Mode accelerates transitions from Active to Idle, delivering up to ~70% power savings to extend battery life in always on workloads.